

ABSTRACT

By dividing a resistor heating body into 2 or more circuits at outer peripheral side and inner peripheral side and feeding different powers to these circuits based on results of temperatures measured through a temperature measuring means to conduct temperature control, the temperature at the outer peripheral side is made equal to or more than the temperature at the inner peripheral side to uniformize the temperature distribution of the substrate heating face in a radial direction and make small a temperature difference of a heating face for silicon wafer.